

13. (New) A wafer polishing head for planarizing a wafer comprising a carrier for loading the wafer, a wafer adhering layer disposed beneath the carrier, a retaining ring surrounding the carrier and the wafer adhering layer, the wafer polishing comprising:

a first pressure chamber having a first inner pressure disposed above the retaining ring;
and

a second pressure chamber having a second inner pressure disposed on the carrier, wherein a relative height between the retaining ring and the carrier can be adjusted by changing the first and second inner pressure.

14. (New) A wafer polishing head for planarizing a wafer comprising a carrier for loading the wafer, a wafer adhering layer disposed beneath the carrier, a retaining ring surrounding the carrier, the wafer adhering layer, a first pressure chamber having a first inner pressure disposed above the retaining ring, and a second pressure chamber having a second inner pressure disposed on the carrier, the wafer polishing comprising:

an automatic control system respectively coupled to the first pressure chamber and the second pressure chamber, the automatic control system comprising converting devices for transforming the first and second inner pressures into feedback digital signals, a controlling device coupled to the converting devices for comparing the feedback digital signals and producing digital signals from the feedback digital signals, and regulating devices coupled to the controlling device for transforming the digital signals into pressure values to adjust a relative height between the carrier and the retaining ring.

15. (New) A wafer polishing head for planarizing a wafer comprising a carrier for loading the wafer, a wafer adhering layer disposed beneath the carrier, a retaining ring surrounding the carrier, the wafer adhering layer, a first pressure chamber having a first inner pressure disposed above the retaining ring, and a second pressure chamber having a second inner pressure disposed on the carrier, the wafer polishing comprising:

an automatic control system respectively coupled to the first pressure chamber and the second pressure chamber for adjusting a relative height between the carrier and the retaining ring.
